L I	Hits	Search Text	DB	Time stamp
Number	111.05			2002/09/20
1	1	5385882.pn.	USPAT; US-PGPUB	2002/08/20 18:12
	1	5297438.pn.	USPAT;	2002/08/20
2	1	5297430.pit.	US-PGPUB	18:12
4	1	5884392.pn.	USPAT;	2002/08/20
1		V // -	US-PGPUB	18:27
5	565	219/385.ccls.	USPAT; US-PGPUB	2002/08/20
İ	_	(("5388945") or ("5954997") or	USPAT;	2002/08/16
_	4	("5388943") Of ("3934997")).PN.	US-PGPUB	15:20
_	3	(("6103625") or ("6046108") or	USPAT;	2002/08/16
:		("6110648")).PN. or (2002/0037642).CCLS.	US-PGPUB	15:26
-	752	414/217.ccls.	USPAT;	2002/08/16
		A14/017 male and /DCP on /nminted add	US-PGPUB USPAT;	2002/08/16
-	9	414/217.ccls. and (PCB or (printed adj circuit adj board))	US-PGPUB	15:34
ļ _	12	1	USPAT;	2002/08/16
	**	circuit adj board)) and component and dry	US-PGPUB	15:52
		and gas		2002/00/16
	1	5388945.pn.	USPAT; US-PGPUB	2002/08/16
	1,	 ("4724874" "4758127" "4776745"	USPAT	2002/08/16
-	11	"4724874" "4758127 4776743 "4923352" "4964776" "4995430"		15:40
	ļ	"5059079" "5064337" "5137063"		
		"5220548" "5284412").PN.		0000/00/25
_	25	5388945.URPN.	USPAT	2002/08/16
	4.075	/hlinn with (DCD on (printed add	USPAT;	2002/08/16
-	1075	(assembling with (PCB or (printed adj	US-PGPUB	15:59
_	76		USPAT;	2002/08/16
	1 , ,	circuit adi board))) and dry	US-PGPUB	16:00
_	3	(assembling with (PCB or (printed adj	USPAT;	2002/08/16
		circuit adj board))) and ((dry or hot)	US-PGPUB	16:03
	276	adj gas) (assembling with component with (PCB or	USPAT;	2002/08/16
_	276	(printed adj circuit adj board)))	US-PGPUB .	16:04
_	2994	((placing or mounting or installing or	USPAT;	2002/08/16
		assembling) with component with (PCB or	US-PGPUB	16:05
		(printed adj circuit adj board)))	ucpam.	2002/08/16
-	1806	((placing or mounting or installing or	USPAT; US-PGPUB	16:06
		assembling) with component with (PCB or (printed adj circuit adj board))) and	OS FGFOD	13.33
		(machine or apparatus)		
_	36		USPAT;	2002/08/16
		assembling) with component with (PCB or	US-PGPUB	16:08
		(printed adj circuit adj board))) and		
		(machine or apparatus) and ((dry or hot) with (gas or ventilation or exhhaust))		
_	66		USPAT;	2002/08/16
		assembling) with (chip or component or	US-PGPUB	16:09
		IC) with (PCB or (printed adj circuit adj		
		board))) and (machine or apparatus) and		
		((dry or hot) with (gas or ventilation or		
1_	17	exhhaust)) ((placing or mounting or installing or	USPAT;	2002/08/16
	1	assembling) with (chip or component or	US-PGPUB	16:12
		IC) with (PCB or (printed adj circuit adj		
		board))) and (machine or apparatus) and		√
		((dry or hot) with (gas or ventilation or		
	7	exhhaust)) and (storage or stock) ((machine or apparatus) with (placing or	USPAT;	2002/08/16
-	1 '	mounting or installing or assembling)	US-PGPUB	16:16
		with (chip or component or IC) with (PCB		
	1	or (printed adj circuit adj board))) and		111
		((dry or hot) with (gas or ventilation or		
		exhhaust)) and (storage or stock)		

				1 2 2 2 2 10 2 12 2 2 2 2 2 2 2 2 2 2 2
_	613	((machine or apparatus) with (placing or	USPAT;	2002/08/16
		mounting or installing or assembling)	US-PGPUB	16:17
		with (chip or component or IC) with (PCB		
		or (printed adj circuit adj board)))		
-	23		USPAT; '	2002/08/16
		mounting or installing or assembling)	US-PGPUB	16:43
		with (chip or component or IC) with (PCB		
		or (printed adj circuit adj board))) and		
		((dry or hot) with (gas or ventilation or		
]	exhhaust))		
- .	8		USPAT	2002/08/16
		"5396334" "5420691" "5457538"		16:22
1		"5519496" "5541834").PN.		2002/02/16
] -	8	5903662.URPN.	USPAT	2002/08/16
			HCD2M.	16:23
[-]	200		USPAT;	2002/08/16
]		apparatus or method or process) with	US-PGPUB	16:51
		(feeding or plac\$3 or mount\$3 or		
		install\$3 or assembl\$3 or insert\$3 or		
		put\$4) with (chip or component or IC)		
		with (PCB or (circuit adj board))) and ((dry or hot) with (gas or ventilation or		
])]	exhhaust)		
	۱ ۸۵		USPAT;	2002/08/16
-	49	apparatus or method or process) with	US-PGPUB	16:55
		(feeding or plac\$3 or mount\$3 or	02 19100	10.55
		install\$3 or assembl\$3 or insert\$3 or		
		put\$4) with (chip or component or IC)	,	
		with (PCB or (circuit adj board))) and		
1		((dry or hot) with (gas or ventilation or		
		exhhaust)) and (moisture or humidity)		
	4	(("6059170") or ("6284996") or	USPAT;	2002/08/19
-		("5903662") or ("6246789")).PN.	US-PGPUB	09:21
<u> </u>	2	(("5388945") or ("5884392")).PN.	USPAT;	2002/08/19
	_	(0000310 / 02 (0001032 //	US-PGPUB	09:21
_	1	5364045.pn.	USPAT;	2002/08/19
			US-PGPUB	12:06
_	10	("1848859" "3603528" "3798657"	USPAT	2002/08/19
		"3920394" "4513862" "5014929"		12:04
		"5038934" "5046674" "5123608"		
		"5195689").PN.		
-	2	5364045.URPN.	USPAT	2002/08/19
				12:58
-	179	242/588.6.ccls.	USPAT;	2002/08/19
]			US-PGPUB	12:11
1-	30	242/588.6.ccls. and component	USPAT;	2002/08/19
			US-PGPUB	12:14
-	1051	(29/739-742).ccls. and component	USPAT;	2002/08/19
			US-PGPUB	12:15
-	786	(29/739-742).ccls. and component and (pcb	USPAT; `	2002/08/19
		or (circuit adj board))	US-PGPUB	12:16
-	13	(29/739-742).ccls. and component and (pcb	USPAT;	2002/08/19
	_	or (circuit adj board)) and dry	US-PGPUB	12:20
-	2	(29/760).ccls. and component and (pcb or	USPAT;	2002/08/19
1	_1_	(circuit adj board)) and dry	US-PGPUB	12:21
- .	52	(29/832).ccls. and component and (pcb or	USPAT;	2002/08/19
	_	(circuit adj board)) and dry	US-PGPUB	12:46
-	0	(29/829+).ccls. and component and (pcb or	USPAT;	2002/08/19
		(circuit adj board)) and dry	US-PGPUB	12:46
-	1	5364045.pn.	USPAT	2002/08/19
		//diamanaina an mlagina an manatina an	HCDATT.	12:58
-	66	((dispensing or placing or mounting or	USPAT;	2002/08/19
		installing or assembling) with (chip or	US-PGPUB	13:05
		component or IC or (surface adj mount adj		
ļ		device)) with (PCB or (printed adj		
		circuit adj board))) and (machine or		
		apparatus) and ((dry or hot) with (gas or		
	l	ventilation or exhhaust))	l	

			<u> </u>	
-	0	(pick adj place adj (component or device	USPAT;	2002/08/20
		or machine)) and (moisture or humidity)	US-PGPUB	09:15
		and (dry adj (gas or atmosphere)) and		
		(PCB or (circuit adj board))		
_	541	(pick adj place adj (component or device	USPAT;	2002/08/20
		or machine))	US-PGPUB	09:16
-	39	(pick adj place adj (component or device	USPAT;	2002/08/20
		or machine)) and (moisture or humidity)	US-PGPUB	09:17
-	0	(pick adj place adj (component or device	USPAT;	2002/08/20
	ł	or machine)) and (moisture or humidity)	US-PGPUB	09:18
	_	and (dry adj (gas or atmosphere))		1 0000 (00 (00
-	9	(pick adj place adj (component or device	USPAT;	2002/08/20
		or machine)) and (moisture or humidity)	US-PGPUB	09:20
	1	and (PCB or (circuit adj board)) and		
		(dry)	HCDAM.	2002/08/20
-	0	(pick adj place adj (component or device or machine)) and (moisture or humidity)	USPAT; US-PGPUB	09:21
			US-PGPUB	09.21
	1	and (PCB or (circuit adj board)) and		
		((hot or dry) adj (exhaust or gas or atmosphere))		
	27		USPAT;	2002/08/20
İ -	"	or machine)) and (moisture or humidity)	US-PGPUB	18:28
1	1	and (PCB or (circuit adj board))	05 1 3 1 0 1	10.20
1_	13	("3815251" "4705311" "4769904"	USPAT	2002/08/20
1	13	"4860438" "4951400" "5323528"	JULAI	09:26
1		"5446960" "5449265" "5524765"		
		"5605430" "5613632" "5732478"		
		"5778524").PN.		
1_	1	219/\$.ccls. and (pick adj place adj	USPAT;	2002/08/20
	-	(component or device or machine)) and	US-PGPUB	09:49
		(moisture or humidity) and (PCB or	1	1
1	i i	(circuit adj board))		
	1	6054682.pn. and (pick adj place adj	USPAT;	2002/08/20
	_	(component or device or machine)) and	US-PGPUB	11:28
		(moisture or humidity) and (PCB or		
		(circuit adj board)) and tray		
_	0	6054682.pn. and (pick adj place adj	USPAT;	2002/08/20
		(component or device or machine)) and	US-PGPUB	11:36
		(moisture or humidity) and (PCB or		
		(circuit adj board)) and tray and bulk		
1 -	0	6054682.pn. and sensor	USPAT;	2002/08/20
			US-PGPUB	11:36
1 -	4731	(sensor near (humidity or moisture or	USPAT;	2002/08/20
1	İ	vapor))	US-PGPUB	11:48
	0	(sensor near (humidity or moisture or	USPAT;	2002/08/20
1		vapor)) and (5884392.pn. or 5388945.pn.)	US-PGPUB	11:48
-	96	(sensor near (humidity or moisture or	USPAT;	2002/08/20
		vapor)) and (dry adj gas)	US-PGPUB	11:50
-	221	(sensor near (humidity or moisture or	USPAT;	2002/08/20
		vapor)) and ((hot or dry) adj (delivery	US-PGPUB	11:51
		or exhaust or gas or atmosphere))		1 2000 /22 /22
-	205	'	USPAT;	2002/08/20
1		vapor)) and ((hot or dry) adj (delivery	US-PGPUB	11:52
		or exhaust or gas or atmosphere)) and		
	_	control		1 2002 (22 (22
-	7		USPAT;	2002/08/20
		vapor)) and ((hot or dry) adj (delivery	US-PGPUB	12:13
		or exhaust or gas or atmosphere)) and		
		control and (PCB or (circuit adj board))		2002/08/22
-	33		USPAT;	2002/08/20
		vapor)) and (((hot or dry) adj (delivery	US-PGPUB	12:32
		or exhaust or gas or atmosphere)) with		
1	_	control)	WGD2 TT	2002/02/20
-	1		USPAT;	2002/08/20
		vapor)) and (((hot or dry) adj (delivery	US-PGPUB	12:33
]		or exhaust or gas or atmosphere)) with		
1 .		control) and 5365779.pn.	<u> </u>	

-	0	(sensor near (humidity or moisture or vapor)) and (((hot or dry) adj (delivery	USPAT; US-PGPUB	2002/08/20 12:34
		or exhaust or gas or atmosphere)) with control) and 5365779.pn. and (PCB or		
	1	(circuit adj board))	•	
-	0	(sensor near (humidity or moisture or	USPAT;	2002/08/20
		vapor)) and (((hot or dry) adj (delivery	US-PGPUB	12:34
		or exhaust or gas or atmosphere)) with		
		control) and 5365779.pn. and (wafer or chip or semiconductor or SMD or PCB or		†
	İ	(circuit adj board))		
_	8	(sensor near (humidity or moisture or	USPAT;	2002/08/20
		vapor)) and (((hot or dry) adj (delivery	US-PGPUB	15:00
		or exhaust or gas or atmosphere)) with	:	
		control) and (wafer or chip or semiconductor or SMD or PCB or (circuit		
	ĺ	adj board))		
_	11604	(humidity or moisture or vapor) same	USPAT;	2002/08/20
		percentage	US-PGPUB	15:01
-	3533	(remove or removed or removing or dry or	USPAT;	2002/08/20
		dried or drying) same (humidity or moisture or vapor) same percentage	US-PGPUB	15:02
_	834	((remove or removed or removing or dry or	USPAT;	2002/08/20
		dried or drying) with (humidity or	US-PGPUB	15:04
		moisture or vapor) with percentage)		
-	131		USPAT;	2002/08/20
		dried or drying) with (humidity or	US-PGPUB 、	15:06
		moisture or vapor) with percentage) and (wafer or chip or semiconductor or SMD or		
1		PCB or (circuit adj board))		
_	810		USPAT;	2002/08/20
		dried or drying) with (humidity or	US-PGPUB	15:07
		moisture or vapor) with (percent or		
	1	percentage)) and (wafer or chip or semiconductor or SMD or PCB or (circuit		
		adj board))		
_	325	1 ' '	USPAT;	2002/08/20
		dried or drying) with (humidity or	US-PGPUB	15:08
		moisture or vapor) with (percent or		
	i	percentage)) and (wafer or (component adj chip) or semiconductor or SMD or PCB or		
		(circuit adj board))		
_	333		USPAT;	2002/08/20
		removed or removing or dry or dried or	US-PGPUB	16:26
		drying) with (humidity or moisture or		
		vapor) with (percent or percentage)) and (wafer or (component adj chip) or		
		semiconductor or SMD or PCB or (circuit		
		adj board))	_	
-	0	(percent or percentage) and 6054682.pn.	USPAT;	2002/08/20
	_		US-PGPUB	15:36
-	0	(percent or percentage) and 5365779.pn.	USPAT; US-PGPUB	2002/08/20 15:36
	0	(((eliminate or eliminating or remove or	US-PGPUB USPAT;	2002/08/20
		removed or removing or dry or dried or	US-PGPUB	16:30
		drying) adj (humidity or moisture or		
		vapor)) with (percent or percentage)) and		
		(wafer or (component adj chip) or		
		semiconductor or SMD or PCB or (circuit adj board)) and (dry adj (gas or		
		atmosphere))		
-	46	(((eliminate or eliminating or remove or	USPAT;	2002/08/20
		removed or removing or dry or dried or	US-PGPUB	16:35
1		drying) adj (humidity or moisture or		.
		vapor)) with (percent or percentage)) and (wafer or (component adj chip) or		
		semiconductor or SMD or PCB or (circuit		
		adj board))		

Г	-	7	(((eliminate or eliminating or remove or	USPAT;	2002/08/20
			removed or removing or dry or dried or	US-PGPUB	16:31
			drying) adj (humidity or moisture or		
1			vapor)) with (percent or percentage)) and		
			(dry adj (gas or atmosphere))		
1	_	1	3809924.pn. and (percent or percentage)	USPAT;	2002/08/20
			-	US-PGPUB	18:11